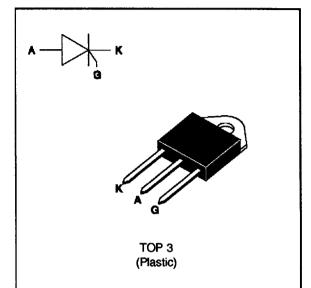


# BTW 69 (N)

### SCR

#### FEATURES

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- BTW 69 Serie : INSULATED VOLTAGE = 2500V(RMS) (UL RECOGNIZED : E81734)



#### DESCRIPTION

The BTW 69 (N) Family of Silicon Controlled Rectifiers uses a high performance glass passivated technology.

This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.

Symbol	Parameter	Value	Unit		
IT(RMS)	RMS on-state current (180° conduction angle)	BTW 69 BTW 69 N	Tc=70°C Tc=75°C	50 55	A
<sup>I</sup> T(AV)	Average on-state current (180° conduction angle,single phase circuit)	Tc=70°C Tc=75°C	32 35	A	
тѕм	Non repetitive surge peak on-state curren	tp=8.3 ms	525	A	
	(Tj initial = 25°C)		tp=10 ms	500	]
l <sup>2</sup> t	l <sup>2</sup> t value tp=10 ms			1250	A <sup>2</sup> s
dl/dt	Critical rate of rise of on-state current Gate supply : $I_G = 100 \text{ mA} \text{ di}_G/\text{dt} = 1 \text{ A}$	100	A/µs		
Tstg Tj	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 125	℃ ℃
ТІ	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			230	°C

#### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	BTW 69		BTW 69 / BTW 69 N				Unit
		200	400	600	800	1000	1200	
VDRM VRRM	Repetitive peak off-state voltage Tj = 125 °C	200	400	600	800	1000	1200	v

March 1995

1/5

#### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-a)	Junction to ambient		50	•C/W
Rth (j-c) DC	Junction to case for DC	BTW 69	0.9	•C/W
		BTW 69 N	0.8	

#### GATE CHARACTERISTICS (maximum values)

 $P_{G} (AV) = 1W \quad P_{GM} = 40W (tp = 20 \ \mu s) \quad I_{FGM} = 8A (tp = 20 \ \mu s) \quad V_{RGM} = 5 \ V.$ 

#### **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions			Value		Unit	
					BTW 69	BTW 69 N	
<sup>I</sup> GT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω		Tj=25°C	MAX	80		mA
VGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33	Ω	Tj=25⁰C	MAX	1.5		v
VGD	VD=VDRM RL=3.3kΩ		Tj= 125°C	MIN	0.2		v
tgt	VD=VDRM IG = 200mA dIG/dt = 1.5A/µs		Tj=25℃	TYP	2		μs
١Ļ	IG= 1.2 IGT		Tj=25°C	ТҮР	50		mA
Н	IT= 500mA gate open		Tj=25°C	MAX	150		mA
V™	BTW 69 ITM= 100A BTW 69 N I <sub>TM</sub> = 110A tp= 380µs		Tj=25°C	MAX	1.9	2.0	v
DRM	VDRM Rated		Tj=25°C	MAX	0.02		mA
IRRM	VRRM Rated		Tj= 125°C		6		
dV/dt	Linear slope up to VD=67%VDRM gate open	V <sub>DRM</sub> ≤ 800V V <sub>DRM</sub> ≥ 1000V	Tj= 125°C	MIN	500 250		V/µs
tq	VD=67%VDRM ITM= 110A VR= 75V dITM/dt=30 A/μs dVD/dt= 20V/μs		Tj= 125⁰C	ТҮР	100		μs



Package	T(RMS)	VDRM / VRRM	Sensitivity Specification		
	A	V	BTW		
BTW 69	50	200	x		
(Insulated)		400	x		
		600	x		
		800	X		
		1000	X		
		1200	X		
BTW 69 N	55	600	Х		
(Uninsulated)		800	x		
		1000	x		
		1200	х		

Fig.1 : Maximum average power dissipation versus average on-state current (BTW 69).

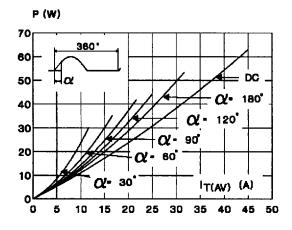


Fig.3 : Maximum average power dissipation versus average on-state current (BTW 69 N).

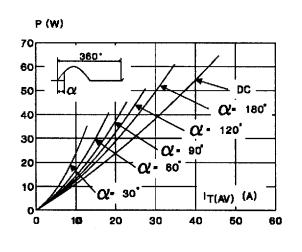


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures (T<sub>amb</sub> and T<sub>case</sub>) for different thermal resistances heatsink + contact (BTW 69).

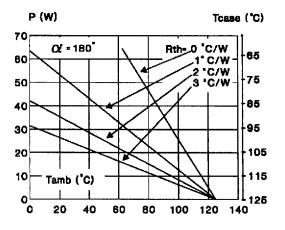


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (BTW 69 N).

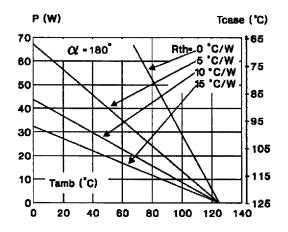


Fig.5 : Average on-state current versus case temperature (BTW 69).

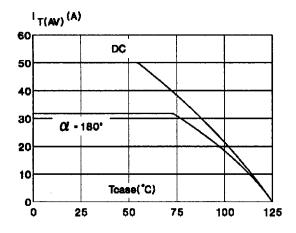


Fig.7 : Relative variation of thermal impedance versus pulse duration.

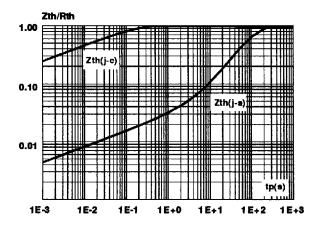
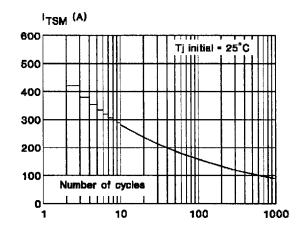


Fig.9 : Non repetitive surge peak on-state current versus number of cycles.



4/5

Fig.6 : Average on-state current versus case temperature (BTW 69 N).

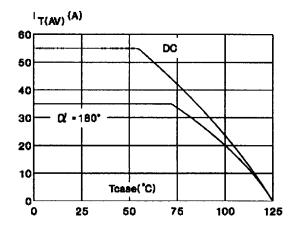
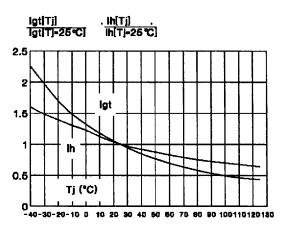
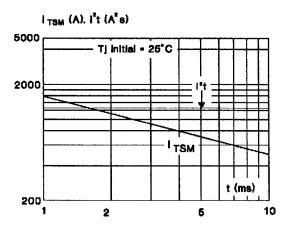


Fig.8 : Relative variation of gate trigger current versus junction temperature.

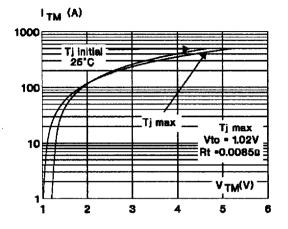


**Fig.10 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \le 10$  ms, and corresponding value of I<sup>2</sup>t.



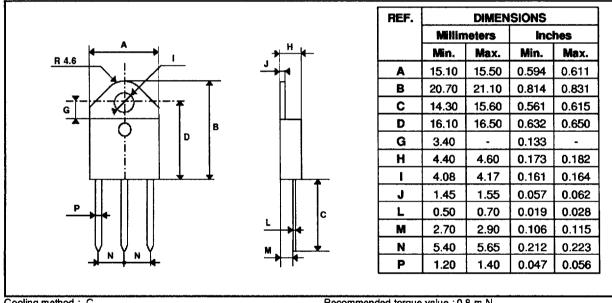
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Fig11 : On-state characteristics (maximum values).



#### PACKAGE MECHANICAL DATA

**TOP3** Plastic



Cooling method : C Marking : type number Weight : 4.7 g Recommended torque value : 0.8 m.N. Maximum torque value : 1 m.N.

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